### PATENT ASSIGNMENT

## Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Dean Baker	05/20/2011
Catherine Ramsdale	05/18/2011
Martin Lewis	05/04/2011

#### RECEIVING PARTY DATA

Name:	Plastic Logic Limited
Street Address:	34 Cambridge Science Park, Milton Road
City:	Cambridge
State/Country:	UNITED KINGDOM
Postal Code:	CB4 0FX

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13124207

#### CORRESPONDENCE DATA

Fax Number: (303)265-9600

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 720-266-4728

Email: DHAMILTON@hdciplaw.COM

Correspondent Name: Douglas M. Hamilton
Address Line 1: 8601 W. CROSS DRIVE

Address Line 2: F5-301

Address Line 4: LITTLETON, COLORADO 80123

ATTORNEY DOCKET NUMBER:	PLAST-000110

### NAME OF SUBMITTER: Douglas M. Hamilton

Total Attachments: 3

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> PATENT REEL: 026401 FRAME: 0072

OF \$40.00 13124207

## ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We, Dean Baker, Catherine Rumsdale, and Martin Lewis hereby sell, assign and transfer to Plastic Logic Limited having offices at: 34 Cambridge Science Park, Milton Road, Cambridge, Cambridgeshire, CB4 0FX, UK and its successors, assigns and legal representatives (collectively "Assignee"), the entire right, title and interest, for the United States, in and to any and all inventions and improvements ("Inventions") as described and/or claimed in an application for Letters Patent of the United States of America entitled "Method and Apparatus for the Formation of an Electronic Device" filed as US Patent Application No. 13/124,207, and in and to the application and all divisional, continuing, substitute, renewal, reissue, reexamination and all other applications for Letters Patent which have been or shall be filed in the United States, and all the rights and privileges under any and all Letters Patent that may be granted therefore including any reissues, reexaminations and extensions thereof.

I/We agree that when requested will, without charge to Assignee but at its expense, sign all papers, take all rightful oaths, make all rightful declarations and do all acts which may be necessary, desirable or convenient for securing and maintaining patents or other forms of protection for the Inventions in any and all countries and for vesting title thereto in Assignee.

I/We hereby consent that a copy of this Assignment Agreement shall be deemed a full legal and formal equivalent of any assignment, consent to file or similar document which may be required in any country for any purpose, including proof of the right of Assignee to apply for patent or other form of protection for the Inventions and to claim the aforesaid benefit of the right of priority.

IN WITNESS WHEREOF, I/we have hereunto signed my/our name(s) on the day and year set forth below.

D. B. Bell		
Inventor Signature	Inventor Signature	Inventor Signature
Dean Baker	Catherine Ramsdale	Wartin Lewis
20/5/2011.		
Date / /	Date	Date

PATENT REEL: 026401 FRAME: 0073

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IN WITNESS WHEREOF, I/we have hereunto signed my/our name(s) on the day and year set forth below.

 $\Delta$ 

Inventor Signature	Otherne Kamadala Inventor Signature	Inventor Signature
Dean Baker	Catherine Ramsdale	Martin Lewis
Date	18 15 /11 . Date	Date

PATENT REEL: 026401 FRAME: 0074

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		Many
Inventor Signature	Inventor Signature	Inventor Signature
Dean Baker	Catherine Ramsdale	Martin Lewis
		4/5/11
Date	Date	Date

RECORDED: 06/07/2011

PATENT REEL: 026401 FRAME: 0075